

# BCM4322/BCM4323





## 802.11n DRAFT 2.0 SINGLE-CHIP SOLUTION

#### **FEATURES**

- Single-chip all-in-one die Baseband/MAC/Radio for 2x2 802.11n applications
- Advanced 65 nm CMOS process for lowest power consumption and highest integration
- 802.11n Draft 2.0 compliant Wi-Fi® solution. Fully compatible with IEEE 802.11n Draft 1.0 and 802.11a/b/g legacy devices.
- Two transmitters and two receivers with optional 802.11n Draft 2.0 modes allow data rates supporting 300 Mbps.
- Flexible two and three antenna configurations for improved range and performance
- Support for optional 802.11n features for improved rate, range performance
  - Greenfield preamble
  - Space Time Block Code (STBC)
  - Short Guard Interval
- Multiple Host Interfaces supported: PCIeTM, PCI, mini PCI, USB 2.0 (BCM94323 only)
- Integrated ARM® Cortex-M3TM CPU for USB host offload
- Low RBOM count and optimal packaging for cost-effective PCB designs
- High-performance 802.11a/b/g/n features standard across the Intensi-fi^M and AirForce  $^{\circledR}$  product lines
  - OneDriver<sup>TM</sup>
    - Single driver across platforms simplifies driver update process and improves customer satisfaction
  - BroadRange™
  - Afterburner<sup>TM</sup> high-speed modes

  - High-performance whole home coverage SecureEasySetup<sup>®</sup> and Wi-Fi protected setup for simple Wi-Fi setup and security configuration
  - WPATM/WPA2TM
  - Cisco® Compatible Extensions (CCXv4, CCXv5)
    Full-rate AES engine in hardware
    WMM® for quality of service

### SYSTEM/CHIP BENEFITS

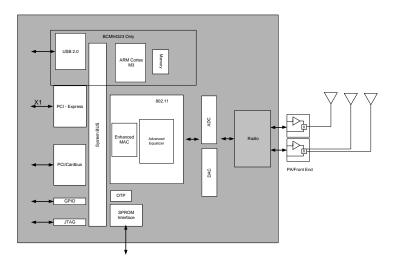
- Single-chip 65-nm solution and high system integration drives down the cost of 802.11n solutions to enable a new generation of media/consumer applications
- CMOS integration and low power modes results in a 50% power reduction compared to previous generation solutions
- Ultra-low RBOM count is 40% lower than previous generation Broadcom 802.11n solutions for small form-factor modules
- Upgradable architecture reduces manufacturing test time and to address the 802.11n standardization process
- Increased rate/range provides user satisfaction and reduces product support call volume
- Self-calibrating architecture allows high yield board manufacturing
- 2x2 antenna structure maintains form-factor compatibility with high volume 802.11a/g industrial designs
- Low-cost CMOS implementation for MAC, Baseband and Radio allows integration with Broadcom's Cable/DSL/Set-top/VoIP chipsets
- Designs meet Pb-free/RoHS worldwide requirements



**BCM4322 PCI Express Half Mini Card Implementation** 



### OVERVIEW



### BCM94322/BCM94323 System Block Diagram

#### BCM94322/BCM94323 Specifications

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